

AMENDMENT NO. 1 DECEMBER 2024
TO
IS 13730 (PART 36) : 2017/IEC 60317-36 : 2013 SPECIFICATIONS FOR
PARTICULAR TYPES OF WINDING WIRES
PART 36 SOLDERABLE POLYESTERIMIDE ENAMELLED ROUND COPPER
WIRE, CLASS 180, WITH A BONDING LAYER

This amendment of IS 13730 (Part 36) : 2017 is identical to merged Amendment No. 1 (2019) and Amendment No. 2 (2024) of IEC 60317-36 : 2013 issued by International Electrotechnical Commission (IEC).

Price Group 2

Foreword

Add the following statement to the Foreword:

This International Standard is to be used in conjunction with IEC 60317-0-1:2013 and its Amendment 1:2019.

2 Normative references

Replace the existing text by the following text and footnote:

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60317-0-1¹:2013, *Specifications for particular types of winding wires – Part 0-1: General requirements – Enamelled round copper wire*.
IEC 60317-0-1:2013/AMD1:2019

¹ There exists a consolidated edition 4.1:2021 that includes IEC 60317-0-1:2013 and its Amendment 1:2019.

3.1 Terms and definitions

Replace the existing text by the following:

"For the purposes of this document, the terms and definitions given in IEC 60317-0-1 apply.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>"

3.2.1 Test methods

Replace the existing title and text by the following:

3.2.1 Methods of test

Subclause 3.2.1 of IEC 60317-0-1:2013 and IEC 60317-0-1:2013/AMD1:2019 applies.

In case of inconsistencies between IEC 60317-0-1 and this document, IEC 60317-36 shall prevail.

5 Electrical resistance

Replace the existing text by the following:

Clause 5 of IEC 60317-0-1:2013 and IEC 60317-0-1:2013/AMD1:2019 applies.

17 Solderability

Replace the content of this clause by the following:

17.1 General

The temperature of the solder bath shall be (470 ± 5) °C. The surface of the tinned wire shall be smooth and free from holes and enamel residues.

17.2 Nominal conductor diameters up to and including 0,100 mm

The maximum immersion time shall be 3 s.

17.3 Nominal conductor diameters over 0,100 mm

The maximum immersion time (in seconds) shall be the following multiple of the nominal conductor diameter (in millimetres) with a minimum of 3 s.

Grade 1B	Grade 2B
12 s/mm	16 s/mm

18.2 Solvent bonding

Replace the existing text by the following:

No requirements apply.